NCE P-Channel Enhancement Mode Power MOSFET

Description

The NCE2305A uses advanced trench technology to provide excellent $R_{\rm DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

General Features

• $V_{DS} = -12V, I_D = -4.1A$

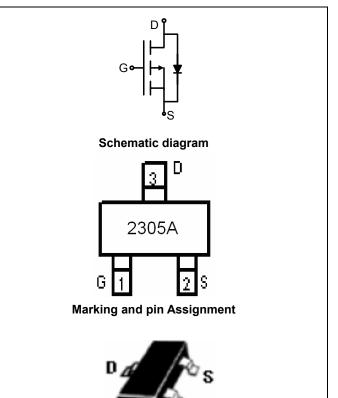
 $R_{DS(ON)}$ < 60m Ω @ V_{GS} =-2.5V

 $R_{DS(ON)} < 45 m\Omega$ @ V_{GS} =-4.5V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- PWM applications
- Load switch
- Power management



SOT-23 top view

Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2305A	NCE2305A	SOT-23	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (TA=25℃unless otherwise noted)

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Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-12	V
Gate-Source Voltage	V _{GS}	±12	V
Drain Current -Continuous	I _D	-4.1	А
Drain Current -Pulsed (Note 1)	I _{DM}	-15	А
Maximum Power Dissipation	P _D	1.7	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	℃

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	74	°C/W

Electrical Characteristics (TA=25°C unless otherwise noted)

	Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics							



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NCE2305A

Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-12	-18	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V,V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250μA	-0.45	-0.7	-1.0	V
Drain Source On State Decistance	В	V _{GS} =-4.5V, I _D =-4.1A - V _{GS} =-2.5V, I _D =-3A -		29	45	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}			40	60	
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-2A	5	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ - 4\/\/ -0\/	-	740	-	PF
Output Capacitance	Coss	V_{DS} =-4V, V_{GS} =0V, F=1.0MHz	-	290	-	PF
Reverse Transfer Capacitance	C _{rss}	F-1.0WIFIZ	-	190	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	12	-	nS
Turn-on Rise Time	t _r	V_{DD} =-4V, I_{D} =-3.3A ,	-	35	-	nS
Turn-Off Delay Time	t _{d(off)}	R_L =-1.2 Ω , V_{GEN} =-4.5 V , R_g =1 Ω	-	30	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Qg		-	7.8	-	nC
Gate-Source Charge	Qgs	V _{DS} =-4V,I _D =-4.1A,V _{GS} =-4.5V	-	1.2	-	nC
Gate-Drain Charge	Q_{gd}		-	1.6	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-1.6A	-	-	-1.2	V
Diode Forward Current (Note 2)	I _S		-	-	4.1	Α
		•				

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

Pb Free Product



Typical Electrical and Thermal Characteristics

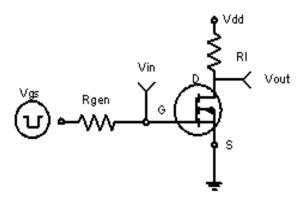


Figure 1:Switching Test Circuit

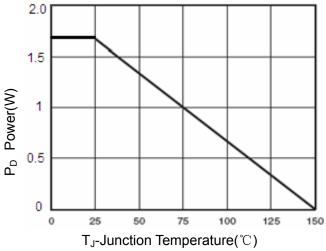


Figure 3 Power Dissipation

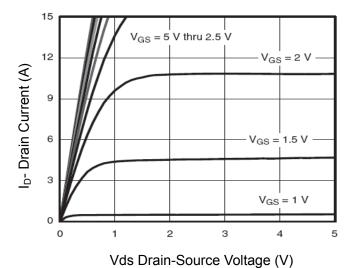


Figure 5 Output Characteristics

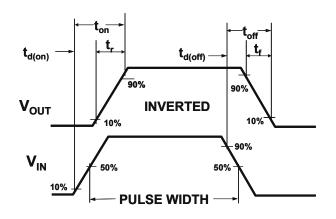


Figure 2:Switching Waveforms

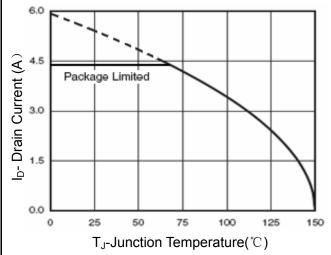


Figure 4 Drain Current

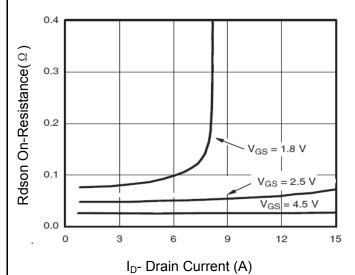
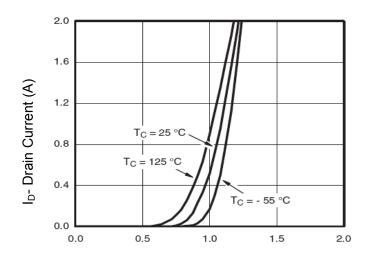


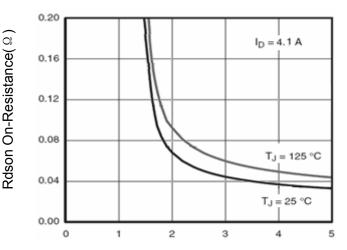
Figure 6 Drain-Source On-Resistance





Vgs Gate-Source Voltage (V)

Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs

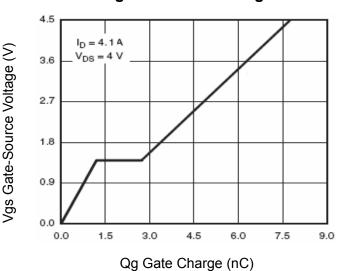


Figure 11 Gate Charge

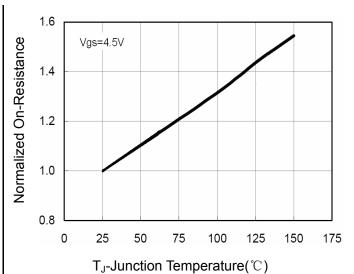


Figure 8 Drain-Source On-Resistance

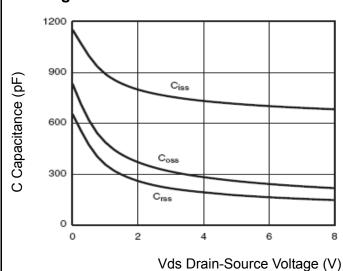
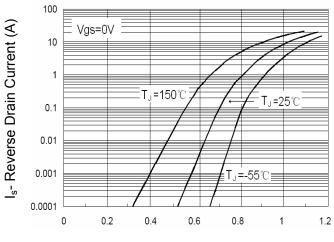


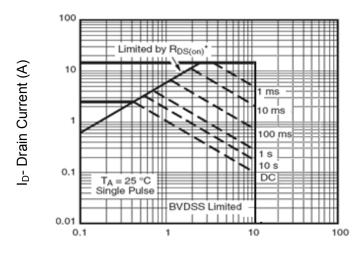
Figure 10 Capacitance vs Vds



Vsd Source-Drain Voltage (V)

Figure 12 Source- Drain Diode Forward





Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area

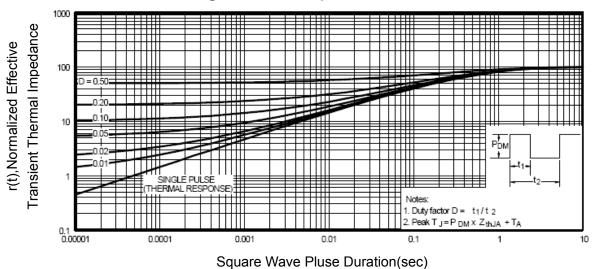
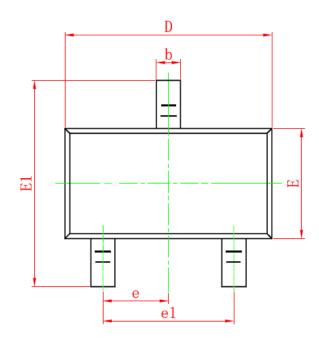


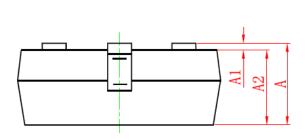
Figure 14 Normalized Maximum Transient Thermal Impedance

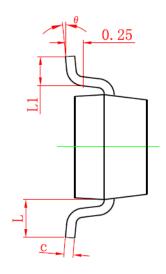
Pb Free Product



SOT-23 Package Information







Symbol	Dimensions in Millimeters			
	MIN.	MAX.		
Α	0.900 1.150			
A1	0.000 0.100			
A2	0.900	1.050		
b	0.300	0.500		
С	0.080 0.150			
D	2.800	3.000		
E	1.200	1.400		
E1	2.250	2.550		
е	0.950TYP			
e1	1.800 2.000			
L	0.550REF			
L1	0.300	0.500		
θ	0° 8°			

Notes

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- 5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



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